AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-12. (Canceled)

Claim 13 (Previously Presented): An electronic parts packaging structure comprising:

a wiring substrate including a wiring pattern;

a first insulation film formed on the wiring substrate;

an electronic parts having a connection terminal on an element formation surface, the electronic parts being buried in the first insulation film in a state where the connection terminal is directed upward and being mounted in a state where a lower portion of the first insulating film exists between the electronic parts and the wiring substrate, and the back side of the electronic parts is electrically insulated with the wiring substrate by the lower portion of the first insulation film;

a second insulation film for covering the electronic parts, and whose upper surface is flat over a whole on the wiring substrate, and the second insulation film contacting with the electronic parts as a single layer, and;

first via holes formed in a predetermined portion of the first and second insulation films on the wiring pattern, and having an identical inner surface;

second via holes formed in a portion of the second insulating film on the connection terminal of the electron parts;

via holes respectively formed in a predetermined portion of the first and second insulation films on the wiring pattern and the connection terminal;

an upper wiring pattern as a single wiring formed on the second insulation film, the upper wiring pattern being connected to the wiring pattern and the connection terminal through the via holes, wherein, the electronic parts is electrically connected to the wiring pattern of the wiring substrate by only the upper wiring pattern; and

an upper electronic part whose bumps are flip-chip bonded to connection portions of the upper wiring pattern, the connection pad which directly contacts the upper surface of the second insulating film.

Claim 14. (Canceled)

Claim 15 (Currently Amended): The electronic parts packaging structure according to ~~claims 13 or 14~~ claim 13, wherein the element formation surface of the electronic parts and an upper surface of the insulation film in which the electronic parts is buried are at an almost same height to be planarized.

Claim 16 (Currently Amended): The electronic parts packaging structure according to ~~claims 13 or 14~~ claim 13, wherein the electronic parts is a semiconductor chip having a thickness of approximately 150 μm or less.

Claim 17 (Currently Amended): The electronic parts packaging structure according to ~~claims 13 or 14~~ claim 13, wherein the insulation film is made of resin.